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TABLE OF CONTENTS

3D Shape Measurements of Patterned Silicon Wafers.....	1
<i>Jan O. Gaudestad, Miguel Jiménez, Kiril Ivanov Kurtev, Juan M. Trujillo-Sevilla, Guillermo Castro Luis, Jose Manuel Ramos-Rodriguez</i>	
Data Variability Study of Advanced 3D NAND Memory Using Python.....	7
<i>Moshe Agam, Henok T Mebrahtu, Himadri Dey</i>	
Using BERT Pre-Trained Image Transformers to Identify Potential Parametric Wafer Map Defects.....	11
<i>En Jen, Yiju Ting, Boris Chen, Ch Jan, Lester Huang, Chingyu Lin, Milton Wu, Anna Feng, Charless Wen, Hw Chen, Jason Yeh, Citi Lai</i>	
Machine Learning Based SEM Image Analysis for Automatic Detection and Classification of Wafer Defects.....	16
<i>Sanghyun Choi, Qian Xie, Nathan Greeneltch, Hyung Joo Lee, Mohan Govindaraj, Srividya Jayaram, Mark Pereira, Sayani Biswas, Samir Bhamidipati, Ilhami Torunoglu</i>	
The Constraint Artificial-Intelligence Assisted Method for Etching Structure Optimization.....	20
<i>Zusing Yang, Ying-Hung Liang, Cheng-En Tsai, Ming-Tsung Wu, Yuan-Chieh Chiu, Hong-Ji Lee, Nan-Tzu Lian, Tahone Yang, Kuang-Chao Chen, Chih-Yuan Lu</i>	
UPC Fault Reduction Via CPEC Backside Surface Roughness Control.....	24
<i>Zeen Vee Ooi, Cheng Wei Alvin Tan, Chin Teck Lim, Murong Peng, Chuah Koh</i>	
TEOS Integrated High-Low Pressure RPS Clean: APC: Advanced Process Control.....	29
<i>Tan Hong Kai, Kenneth Mah Chih Yuang, Chiam Chek Chou, Koh Chuah, Lau Ker Peng, Xie Jun</i>	
A Case of Plasma-Induced Film Breakdown in 3D NAND BEOL Dielectric Etch.....	32
<i>Ying-Hung Liang, Yuan-Chieh Chiu, Zusing Yang, Hong-Ji Lee, Nan-Tzu Lian, Tahone Yang, Kuang-Chao Chen, Chih-Yuan Lu</i>	
Micro- and Macro-domain Analysis of Whole Silicon Carbide Wafers by T-ray Imaging: AM: Advanced Metrology.....	36
<i>Ans Rahman</i>	
BEOL Dielectric Film Delamination Reliability Improvement by Eliminating Silicon-Rich Interface.....	41
<i>Adukkadukkam Dineshan, Jane Chow</i>	
Method of Controlling Interface Oxide in Polysilicon Emitter PNP Bipolar Transistors.....	45
<i>Adukkadukkam Dineshan, Jane Chow, Hiew Hock Hing</i>	
Double-Edged Effect of Aqueous Hydrofluoric Acid (HF) on Silicon Interface Quality.....	49
<i>Ann Ann Boo, Belinda Ng, Mark Teo, Yiwen Zhang, Kiat Sean Tan, Ray Mondina, Chin San Lee</i>	
Wafer Edge RF LNR Yield Improvement in Oxide Etch Applications.....	54
<i>Fook Yen Chai, Li Bo, Kin Wai Tang, Kong Yeow Pang</i>	
Analyzing Time-Dependent Behavior of Wafer Outgassing in the Front Opening Unified Pod.....	59
<i>Ki Dong Yang, Hyunjoo Jeon, Eunyong Han, Youngeun Kim, Sujin Park, Young Jeong Kim, Keungjoo Suk, Jiyun Han, Joong Jung Kim</i>	

Controlling Discharge Condition of PE-SION Deposition Process for Finding a Balance Between NH ₃ Outgassing and Surface-Remained NH ₄ ⁺ ions.....	63
<i>Ki Dong Yang, Keungjoo Suk, Jaein Jeong, Kwangtae Hwang, Joonho H. Lee, Young Jeong Kim, Youngsoo Jung, Young Eun Kim, Joong Jung Kim</i>	
Wafer Substrate Bevel Significance to Edge Yield Performance	66
<i>Shuli Ma, Belinda Ng, Teo Min Hou</i>	
Solution for Pond Shape Defect Near Wafer Edge.....	70
<i>Mei Yen Koe, Juncheng Zhou, Vinod Xavier</i>	
Metal Etch Depth Metrology Using YieldStar and CDSEM	74
<i>Roy Anunciado, Ilirjan Aliaj, Richard Van Haren, Vincent Truffert, Alain Moussa, Danny Goossens, Amir-Hossein Tamaddon</i>	
The Digital Twin Difference - A Blueprint for the Semiconductor Manufacturing Metaverse	78
<i>Urmi Sen, David Gross</i>	
Method to Control Polymer Generation During Thick Top Metal Process to Reduce Sidewall Defects.....	84
<i>Rajkumar Thiruchelvam, Sajidul Haque Siraji, Benedict Cheong</i>	
Auto Furnace Scheduler with Built in Timelink Regulator (Auto Kitter)	89
<i>Tin Zar Tun, Lim Kok Tee</i>	
Optimizing High-Product-Mix Manufacturing with Advanced Process Control Through Machine Learning-Based Virtual Metrology.....	95
<i>Hyung Joo Lee, Sanghyun Choi, Nathan Greeneltch, Srividya Jayaram</i>	
Lithography WEE, EBR and Pre-SiGe HF Clean Flow Rate Optimization for Wafer Edge Defectivity Improvement.....	99
<i>Jane Chow, Dineshan Adukkadukkam, Eng Choon Siong, Derrick Ong, Tan Kiat Sean</i>	
Copper Electromigration Improvement Through Aluminum Barrier and Related Process Optimization.....	103
<i>P B Sahoo, Harri Dharma Hadi, Amirul Afiq, Xie Jun, Chong Chia Yee, Tan Tze Hian, Huang Daiyu, Peck Yan Zheng</i>	
A Particle Reduction Strategy for Plasma Etching Processes.....	106
<i>Jaein Jeong, Younggil Kim, Jiyeon Lee, Youngjeong Kim</i>	
Wafer Edge Unsalicided Poly Resistor Matching Optimization with Spike Anneal Temperature Control.....	110
<i>Xiao Bin Wu, Belinda Ng, Mui Khin Tok, Ker Peng Lau</i>	
Elimination of Passivation RIE Arcing in RFSOI Process	114
<i>Shu Teik Ong, Wai San Loh, Yong Hai Li, Shi Rui Teng, Ghit Guan Goh, Chandrasekar Venkataramani</i>	
Investigation of Power-Down Leakage Bin Fallout Caused by Fixed Location Gate Oxide Pin Hole	118
<i>Jialiang Tang, Mohd Nurul Islam, Tan, Kiat Sean</i>	
MTP Data Retention Improvement by Salicide Clean Optimization.....	122
<i>Si Yien Low, Gong Cheng, Mohd Nurul Islam, Chin San Lee, Xiqiang Li</i>	
Metal Mask Rework Optimization for Metal with TaN Precision Resistor on it.....	126
<i>Jialiang Tang, Mohd Nurul Islam, Moh Moh</i>	

Optimization of O ₂ Plasma After Silicon Etch Process to Prevent Br-Induced Equipment Corrosion and Pattern Abnormality	129
<i>Junseok Kang, Ki Dong Yang, Soobin Sinn, Gyuwon Gim, Hanbit Park, Wookyoung Hwang, Eunyong Han, Young Jeong Kim, Joong Jung Kim</i>	
Design Modification to Mitigate Ethylene Glycol Corrosion Risk in Dry Etching Machine.....	133
<i>Rendy Wiyogo Gozali, Loh Kim Shiang, Thiruchelvam Rajkumar, Joselito Butiu</i>	
ASMC: Improving Measurement Data Quality with Machine Learning	137
<i>Jun Hao Tan, Heng Wah Ho</i>	
Optimization of Area Selective Barrier on Different Metal Interconnects	141
<i>Linda Wangoh, Andrew Simon, Matthew Shoudy</i>	
Innovative Approaches for 3D Metrology and Defect Analysis on Advanced Packaging Structures.....	145
<i>Ivy Wu, Melissa Mullen, Mark McClendon, Pete Carleso, Xiaoting Gu, Mary Wu</i>	
Study of Wafer Arcing Defects on PECVD Low Deposition Rate TEOS Oxide Thin Film	150
<i>Minrui Wang, Irene Low, Yb Lee, Joseph Schmitt</i>	
Electrochemical Innovations for Sustainable Copper Management in Semiconductor Wastewater.....	154
<i>Cameron Lippert, James Landon, Jason Keleher, Alan Rassoolkhani</i>	
Predictive Analysis and Root Cause Identification of Equipment Failures Using Event Log Patterns: A Focus on EUV/DUV Equipment	159
<i>Wanwook Ki, Minjae Choi, Yongjun Lee, Jisoo Park, Ji Jiyeon Park, Jaeyong Park, Younghoon Kim</i>	
Selective Auto-Labeling for Deep Learning-Based Domain-Specific Image Classification in Manufacturing	164
<i>Jisoo Park, Wanwook Ki, Yongjun Lee, Minjae Choi, Ji Jiyeon Park, Jaeyong Park, Younghoon Kim</i>	
Combining Batchespray and Ozone Reduces Chemical Consumption in Wafer Cleaning	169
<i>Bernhard Hammerl</i>	
Advanced Metrology of Thick Silicon Nitride Films at 300 Mm Scale for Next Generation High-Q Photonic Devices.....	175
<i>Soumen Kar, Nicholas W. Gangi, Katrina A. Morgan, Lewis G. Carpenter, Nicholas M. Fahrenkopf, Christopher V. Baiocco</i>	
Periphery Gate Optimization for Reducing Single-Sense Amp (SSA) Failure in DRAM: YE: Yield Enhancement/Learning.....	181
<i>Ketaki Sarkar, Rizwan Tariq, Bryan Orf, William Simpson, Todd Smith, Aayush Mittal, David Macmahon, John Lee, Michael Hurt</i>	
Real-Time Etching Process Monitoring and End-point Detection with a Time-of-flight Mass Spectrometer.....	185
<i>Sébastien Gasc, Federico Binda, Pratyush Das Kanungo, Lukas Hofer, Maximilian Rothenberger</i>	
Feedback Control in Station Dispatching to Improve Constraint Tool Output in 300mm Fabs	189
<i>Murali Krishna, Michael Kalmus, Robert A Madson, Arca Mert, David J Mosgrove, Akanksha T Trimeloni, Christopher J Merrill, Zhili L Zhao</i>	
Highly Selective Si Vs. SiGe and SiGe Vs. Ge Wet Etch for Sub 2nm Applications.....	193
<i>Chien-Pin Sherman Hsu</i>	

Critical Defect Detection at 3nm Technology Node: Enhanced Detection Using DUV Optical Inspection Technology with AI-Based Algorithm	196
<i>Shao-Chien Chiu, Mark Peng, Yuan-Chung Wei, Kai-Yuan Cheng, To-Yu Chen, Heng-Yu Chou, Meng-Che Wu, Kuan Hua Su, Nofar Shushan, Assaf Mizrahi, Sidharth Maurya, Guy Danieli, Gilad Reut</i>	
Dynamic Time Warping Constraints for Semiconductor Processing.....	201
<i>Rachel Owens, Fan-Keng Sun, Christopher Venditti, Daniel Blake, Jack Dillon, Duane Boning</i>	
Sustainability Model for Semiconductor Manufacturing	207
<i>Eason Qi, Tienying Luo, Mallory Wick, Helen Armer, Michael Raiford, Tony Marteniz, Sanjiv Mittal</i>	
Autonomous Robot Orchestration Solution for OHT with Machine Learning and Digital Twin FA: Factory Automation	211
<i>Jinhyeok Park, Donghwi Shin, Sangpyo Hong, Illhoe Hwang, Seol Hwang, Young Jae Jang, Jaeho Lee, Jaeung Lee</i>	
An Implementation of a Machine Learning Methodology for Improving Test Data Quality	217
<i>Heng Wah Ho, Pojcharapol Leenukiat</i>	
First Results from a New Online Nano Liquid Particle Monitor on Ultra-Pure Water	221
<i>Kenneth R. Farmer, Hee-Siew Han, Nathan Birkeland</i>	
Unsupervised Trace-SPC Anomaly Detection Solution Based on VAE Model.....	225
<i>Xiaofei Wang, Hui Jiang</i>	
Process Control Solutions for GaN-On-Si Devices in a Production Line	230
<i>Francesco F. Carboni, Luca M. Perego, Laura T. Czeppel, Daniele Capelli, Bruno Moio, Costanza Adamo, Maddalena Bollin, Luca Barbisan, Francesco Bellando, Matteo M. Salamone, Parikshit Sharma, Paolo Parisi, Shruti Deepak, Manoj K. Dayyala</i>	
Cloud Big Data Lake for Advanced Analytics in Semiconductor Manufacturing	235
<i>Susan Sun, Jeff Ye, Hubert Schwarthoff, Jon Rosin, Varalakshmi Vakkalagadda, Jimmy Chang, Sesidhar Reddy Ubbara, Anil Chinthakindi</i>	
12LP FinFET CMOS Ultra-Low Leakage SRAM Devices with 0.54pA/cell Istby	240
<i>Yuchen Du, Vitor Rossi Vulcano, Yao Yao, Hong Yu, Wei Ma, Owen Hu</i>	
Elimination of Bond Pad Etch Induced Wafer Arcing Via Reducing ESC Chuck Surface Charges.....	245
<i>Jeff J. Ye, Wan-Ping Lien, Ocean Lee, Levi Tsai</i>	
Defect Reduction and Line Width Roughness (LWR) Improvement by Using a Post Precoat Treatment (PPT) in Waferless Chamber Conditioning (WCC)	249
<i>Jeff J. Ye, Raviteja Pagadala, Fei Lu</i>	
Reliable Cu Pillar Undercut Control Using the Endpoint Detection System.....	253
<i>Zachary Gardner, Soon-Cheon Seo, Pijeng Khor, Chris Waskiewicz, M. Sankarapandian, Eric Perfecto, Karthik Pillai, James Demarest</i>	
ScCO ₂ Drying for Preventing Pattern Collapse in Advanced Logic Device Structures	256
<i>M. Sankarapandian, Wei-Shang Lo, Alma Vela Ramirez, Nash Flores, Xuan Liu, Reijiro Yamanaka, Saya Inoue, Shinichiro Shimomura, Koji Iwanaga</i>	

Process Margin Improvement and Cost Saving from a New Plasma Oxide Etch Process with Endpoint Algorithm During Photolithography Positive- to Negative-Tone Develop Conversion.....	260
<i>Jeff J. Ye, Todd Smith, Alex Liew, Arika Fritz, Ketaki Sarkar, Alan Fang</i>	
Rapid Analysis of Organic Contaminants in Semiconductor Process Chemicals and on Wafer Surfaces	264
<i>Briana Dufek, Suhas Ketkar, Tyler Herek, Jake Unnerstall, Derrick Quarles, Kyle Uhlmeyer, Austin Schultz, Dan Wiederin</i>	
In-Situ Post Etch Fluorocarbon Byproduct Removal for HDP Void Reduction	270
<i>Prabhakar Bharatan, Jeff J. Ye, Brad Webb, Lauren Kerstetter, Dave Macmahon, Jason Snead, Doug Poling, Michael Hurt</i>	
Supporting Fab Operations Using Multi-Agent Reinforcement Learning.....	275
<i>Ishaan Sood, Abhinav Kaushik, Tom Bulgerin, Prashant Kumar, Subham Rath, Abdelhak Khemiri, Johnny Chang, Sam Hsu, Jeroen Bédorf</i>	
Reduction of Stiction Using Different Surface Treatment Methods on Elastomers and Their Longevity Studies.....	281
<i>Maïke Khosrawi, Thomas Dunn, Renate Brielmann, Feyzan Durn, Murat Gulcur</i>	
Improvement on the Gate Oxide Integrity Caused by the TUB Charges in SOI Technology	286
<i>Lesley Wong Ying Ying, Charissa Antia Anak Tuloi, Steven John Pilkington, Ryan Lee Hun Jin, Desmond Lau Zhong Hong</i>	
Fault Detection of Wafer Sensors Based on Representation Learning and Isolation Forest.....	290
<i>Haixiang Qiu, Hui Jiang</i>	
Streamlining Critical Queue Timer Management: A Digital Twin Approach to Optimize Frontend Manufacturing	295
<i>Terbrack Hajo, Brandl Holger, Roßbach Philipp</i>	
An Innovative Method and Apparatus for KGSD Testing of 2.5D and 3D Stacked Dies, with Emphasis on High Bandwidth Memory (HBM).....	301
<i>Calvin Park</i>	
In-House Test Wafer Reclaim for Fab Cost and Wastage Reduction: MS: Manufacturing for Sustainability	306
<i>Xinqiao Dong, Subhadeep Mukherjee, Monicka Asokan, Yi Yang, Vivek Duvvuru</i>	
New High Resolution Method to Characterize CMP Slurry Particle Size Distributions	313
<i>Andrea J. Tiwari, Daniel R. Troolin, Atul H. Patel, Justin S. Koczak, Nathan T. Birkeland, Hee-Siew Han</i>	
The Value of In-Line Metrology for Advanced Process Control: AM: Advanced Metrology	319
<i>Jaeho Lee, Mike Young-Han Kim, Yongsoon Eun</i>	
Deploying an Advanced Scheduling Solution to Optimize Conflicting KPIs in the Diffusion Area at Renesas Electronics	323
<i>Semya Elaoud, Lio Weinstock, James Adamson, Dennis Xenos, Jay Maguire</i>	
Big Data Analytics for Real Time Dispatch	329
<i>Himanshu Mogra, Sainikhil Segu, James DeLong, Remy Canales-Vaschy, Srikanth Ramakrishnan, Sriram Sridharan, Srikanth Penumutchu</i>	

Evaluation of Different Metal Preclean Conditions for MOL for 2nm and Beyond: Topic/category: AEPM : Advanced Equipment Processes and Materials	334
<i>Samuel Munnangi, Andrew Simon, Oscar Van Der Straten, Rishi Krishnan, Shahab Siddiqui, Matthew Shoudy</i>	
Understanding DRAM Array Contact Missing: Mechanisms Study with Practical Solutions: YE: Yield Enhancement/Learnin	338
<i>Marvin Tsai, Ketaki Sarkar, Gus Alhomsy, Jacob Manning, Stephen Casey, Gautham Swaminathan, Michael Hurt</i>	
Wet Etch Recipe Optimization for Enabling RMG Multi Vt Scheme	341
<i>Alma Vela Ramirez, M. Sankarapandian, Ruqiang Bao, William Parkin, Takaoka Makoto, Kishimoto Takuya</i>	
Accelerating Chamber-To-Chamber Matching Using AI	344
<i>Emil Pitz, Leandro Medina, Meghali Chopra</i>	
Strategies to Attract the Next Generation of Talent to the Semiconductor Industry	349
<i>Marie Le Guilly, Justine Feist, Faith Isowamwen</i>	
Consideration of a Ga-FIB in Lamella Sample Prep for EBIC Analysis of Advanced-node SRAMs.....	353
<i>Gregory M. Johnson, Andreas Rummel, Heiko Stegmann, Cheryl Hartfield</i>	
Feed-Forward Run-to-Run Process Control Based on Device Array Density for LPCVD Furnace Processes	359
<i>Prabhakar K Bharatan, Farid Sellidj</i>	
Scheduling Semiconductor Manufacturing Operations in Research and Development Environments	364
<i>Valeria Borodin, Vincent Fischer, Agnès Roussy, Claude Yugma</i>	
Effective Downsampling Techniques for SEM Defect Inspection Using Design Insights in Machine Learning: Topic/category: DI: Defect Inspection and Reduction	370
<i>Qian Xie, S Keerthibala Viswanatha, Srividya Jayaram, Sudheesh Krishnankutty, Frederic Huguennet, Rakesh Soni, Aparna Basu</i>	
Using Monte Carlo Simulation - A Predictive Model to Identify Capacity and Cycle Time Detractors in a Semiconductor Foundry	374
<i>Boyd Finlay, Sofia Khudyakov, Vikram Arjunwadkar</i>	
Multi-Objective Sort Job Optimization for Wafer Bonding Tools.....	378
<i>Detlef Pabst, James Delong, Shiladitya Chakravorty, Srikanth Ramakrishnan</i>	
Hafnium Chloride Pulse Time Reduction on Atomic Layer Deposited High-K HfO ₂ Dielectric Films.....	385
<i>Meena Rajachidambaram, Bridgette Rodman, Alyssa Bennett, Justin Clements, Bas Korevaar</i>	
Real-Time Water Leak Detection and Preventing Yield Excursions in Lithography.....	390
<i>Shine Arkar Aung, Liu Houdong, Fazuli Sani</i>	
Process and Tool Monitoring Strategy for Advanced Magnetic Tunnel Junction Stack Deposition	394
<i>Gabriel Rodriguez, Oscar Van Der Straten, Virat Mehta, J. M. Slaughter, Christian Kaiser, Chien-Fu Huang, Dan Frye, Ryan Carr</i>	
Real-Time Balancing of WIP for Compatible Capacities Across Distant Fab Buildings Using Automated Cross-Location Decisions	397
<i>Binay Dash, Detlef Pabst, Viswa Devan Nair Ramadhasan, Alex Wong, Jonathan Lee, Edmund Tan</i>	

Optimization of Scatterometry Measurements by Enhancing with Machine Learning AM: Advanced Metrology	402
<i>Sasmita Srichandan, Franz Heider, Georg Ehrentraut, Stephan Lilje, Christian Putzi, Sanja Radosavljevic, Egidijus Sakalauskas</i>	
Semiconductor Manufacturing Data Synthesis Through GANs.....	408
<i>Brian Tse, Tori Wright, Emmanuel Nsiye, Timothy Azinord, David Medina, Sean Mondesire</i>	
Thickness Description of Thick GaN Film Stack and Measurement of Al Percentage in AlGaN Alloy with KLA SpectraShape™ 10K	414
<i>Giulio Baldi, Francesco De Paola, Isabelle Mongiatti, Andrea Severino</i>	
Coming of Age in Computational SEM.....	419
<i>Benjamin D. Bunday, Shari Klotzkin, Douglas Patriarche, Yvette Ball</i>	
Optimization of FINFET Single Diffusion Break Structure Profile	428
<i>Chunpui Kwan, Hongliang Shen, Sen Ashokmani, Lezhong Gao, Cassidy Dineen, Vishvajeet Vijay Mane, Thilina Dayanga, Cameron Sloan</i>	
Impact of Implantation Conditions on the In-Depth Distribution of Implanted Species in SiC and GaN	432
<i>Laura Creon, Jinlei Ren, Seoyoun Choi, Paula Peres, Matt Pietrucha, Frank Torregrosa, Stephane Morata</i>	
Protocol for Thermal Donors Monitoring in High Resistivity Silicon Wafers	434
<i>Alexandra Abbadie, Alexandre Desse, Kassem Melhem, Simone Dario Mariani, Davide Fagiani, Paola Zualiani, Frank Fallerfrank</i>	
Rapid Thermal Annealing for Shallow Junction and Its Impact on FinFET Integration	440
<i>H. Choi, M. McCutcheon, S. Yin, S. Sugantharaj, H. Sim, B. Korevaar</i>	
Q-Time Assessment on Electroplated Nickel/Gold Interface Quality	444
<i>Sanjoy Paul, Brittany Hedrick, Ahmed Abdel-Aziz, John Garant, Brett Yatzor, Christian Schroiff, Qin Yuan</i>	
Analyses of eSiGe Defects Induced by Outdoor Airborne Nanoparticles	447
<i>Jongmin Lee, Jungtae Park, Il-Jin Kim, Haeun Lee, Sehoon Park</i>	
Leveraging the Data Continuum for Advanced Root Cause Analysis	451
<i>Peter Barar, Eric McCormick</i>	
Probabilistic Modeling and Machine Learning for Preventative Maintenance Prediction in Semiconductor Manufacturing	456
<i>Tori Wright, Brian Tse, Emmanuel Nsiye, Timothy Azinord, David Medina, Sean Mondesire</i>	
Surface Leakage of Zener Diode and Its Degradation Behaviour Due to Diminishing Field Effect Passivation.....	462
<i>Ke Kian Seng Joseph, Priefert Dirk</i>	
Novel Approach Utilizing APIMS Technology for Analyzing CO & H2 Impurities in Semiconductor UHP Gases: AM: Advanced Metrology.....	466
<i>Greg Thier</i>	
Enabling 300 Mm Wafer-Scale Fabrication of Superconducting Quantum Devices.....	468
<i>Ekta Bhatia, Hunter Frost, Nicholas Pieniazek, Jakub Nalaskowski, John Mucci, Wenli Collison, Brian Martinick, Geevanie Telhu, Bryan Egan, Stephen Olson, Pui-Yee Hung, Ilyssa Wells, Corbet Johnson, Thomas Murray, Kevin Musick, Satyavolu Papa Rao</i>	

Novel Chemical Development for Post Metal Etch Clean	474
<i>Lynn Covolo-Whitesell, Yve Han, Sushil Patil, Zahir Alamgir, Devin Freeman, Nicholas Jira, Lukas Kiehl, Sanjna Lakshminarayanamurthy, Nirmal Sundaramoorthy, Satish Singh, Vincent Sih, Hisashi Shinomura, Yoshiyuku Kajiki, Satoshi Kamo, Koji Kawahara, Hiroyuki Tano</i>	
Elimination of Pinhole Defects in Self-Aligned Double Patterning Process by Using Bias Pulsed Plasma	478
<i>Wan-Ping Lien, Jeff J. Ye, You-Shen Wu, Ruby Chiu, Becky Wu</i>	
Difference Image-Based Training Sets for Automatic Defect Classification at Outgoing Inspection	483
<i>Mark Sidorchuk, Nigel Caprotti, Mert Kilicoglu, Panneer Selvam Venkatachalam, Samuel Marble, Brian Trapp, Ping Ping Lau</i>	
Water Vapor Measurements of Ultra-Pure Gases for Critical Manufacturing Processes	488
<i>Jodi Armstrong, Hannu Sairanen</i>	
Die-Level Serialization Platform Demonstration	492
<i>Cedric Canu, Richard Beaudry, Maurice J. A. Delafosse</i>	
AI-Powered Process Optimization for EUV MOR: Equipment Trace Data Feature Extraction and Machine Learning is Essential for CD Control	497
<i>Boyd Finlay, Mario Faria, Steven Gucci, Eric Holzer, Nicholas Latham, Francis Ortega</i>	
NVM Tunnel Oxide Integration in an Advanced BCD Node and Its Impact on GOI	502
<i>Gang Liu, Matthias Lipinski, Sallie Hose, Santosh Menon</i>	
Development of Epitaxial SiGeB as a Test Vehicle to Evaluate Source-Drain Etchout During Channel Release of Gate-all-Around Devices: Topic/category: AEPM: Advanced Equipment Processes and Materials	506
<i>M. Nasser, C. Durfee, J. Li, K. Sieg, S. Schoeche, L. Qin, D. Schmidt, S. Fan, A. Dutta, N. Loubet, E. Miller, L. Meli</i>	
Scatterometry Critical Dimension Solution for Gate All Around Sheet-Specific Metrology: Topic/category: Advanced Metrology	510
<i>Houssam Chouaib, Anderson Chou, Valeria Dimastrodonato, Haomiao Chang, Zhengquan Tan, Derrick Shaughnessy</i>	
A Noble Cause: Reduction of Ne and Xe Consumption for Gas Laser Mixtures: MS: Manufacturing for Sustainability	518
<i>Katja Brockhaus, Henry Bernhardt, Jesus Cesar Calvo Blanco, Stefan Koppetzki, Seita Onishi, Tom Richter, Olaf Storbeck</i>	
DTCO Guided Process Integration: Case Studies from FEOL & BEOL with BSPDN Topic: DTCO/DFM	522
<i>Minhaz Abedin, Shahrukh Khan, Nicholas Lanzillo, Dan Dechene</i>	

Author Index